

0,50mm PITCH BASIC BTH, BSH SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTH or www.samtec.com?BSH

Insulator Material:

Liquid Crystal
Polymer

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over 50μ" (1,27μm) Ni

Current Rating:

1.25A @ 80°C ambient

Flammability Rating:

UL 94 V0

Operating Temp Range:

-55°C to +125°C

Voltage Rating:

125 VAC

Max Cycles:

100

RoHS Compliant:

Yes

Processing:

Max Processing Temp:

230°C for 60 seconds, or

260°C for 20 seconds 3x

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10mm).004" max (030-090)

(0,15mm).006" max (120-150)

Board Stacking:

For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com



BTH

NO. OF POSITIONS PER ROW

01

PLATING OPTION

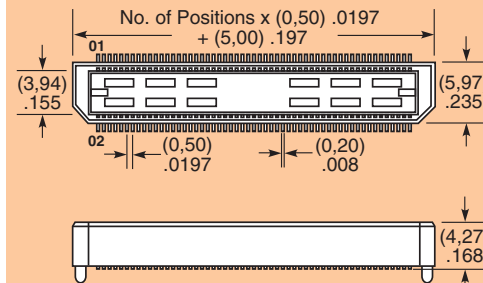
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A

OTHER OPTION

Mates with:
BSH

**-030, -050, -060,
-090, -120, -150**



-L

= 10μ" (0,25μm) Gold on contact, Matte Tin on tail

-F

= Gold Flash on contact, Matte Tin on tail

-C*

= Electro-Polished Selective 50μ" (1,27μm) min Au over 150μ" (3,81μm) Ni on Signal Pins in contact area, 10μ" (0,25μm) min Au over 50μ" (1,27μm) Ni on Ground Plane in contact area, Matte Tin over 50μ" (1,27μm) min Ni on all solder tails

-K

= (7,00mm) .276" DIA Polyimide Film Pick & Place Pad

-TR

= Tape and Reel (120 positions maximum)

APPLICATION SPECIFIC

- 30μ" (0,76μm) Gold
- Edge Mount Capability
- 8mm, 11mm, 16mm, 19mm and 22mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11mm, 16mm, 19mm and 22mm not available with 50 positions)

Call Samtec.

BSH

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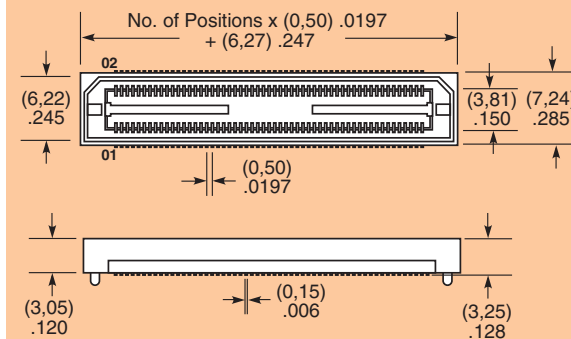
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AGILENT LOGIC ANALYZER TEST POINT CONNECTOR

Specify: ASP-65067-01

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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